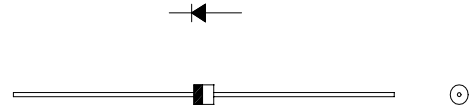


# FRD Type :10ERA60

## OUTLINE DRAWING

### FEATURES

- \* Miniature Size
- \* Super Fast Recovery
- \* Low Power Loss, High Efficiency
- \* High Surge Capability
- \* 26mm and 52mm Inside Tape Spacing



### Maximum Ratings

Approx Net Weight:0.17g

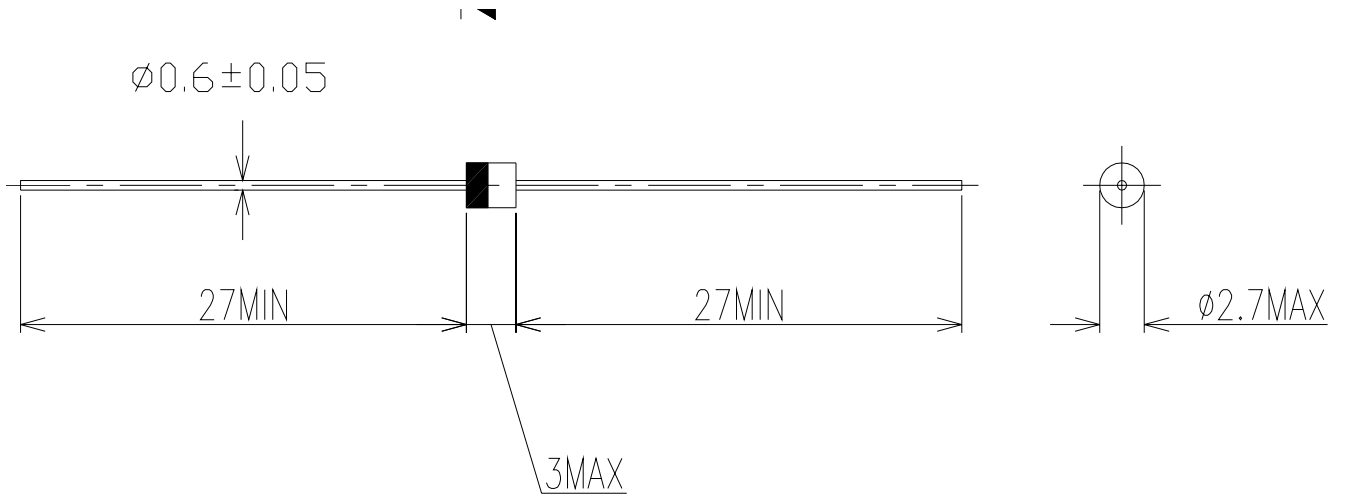
Rating	Symbol	10ERA60			Unit	
Repetitive Peak Reverse Voltage	$V_{RRM}$	600			V	
Average Rectified Output Current	-	$I_O$	1.0	$T_l=118^{\circ}\text{C}$	Half Sine Wave	A
			0.96	$T_a=26^{\circ}\text{C} *1$	Resistive Load	
RMS Forward Current	$I_{F(RMS)}$	1.57			A	
Surge Forward Current	$I_{FSM}$	30	Half Sine Wave, 1 cycle, Non-repetitive		A	
Operating Junction Temperature Range	$T_{jw}$	- 40 to + 150			$^{\circ}\text{C}$	
Storage Temperature Range	$T_{stg}$	- 40 to + 150			$^{\circ}\text{C}$	

### Electrical • Thermal Characteristics

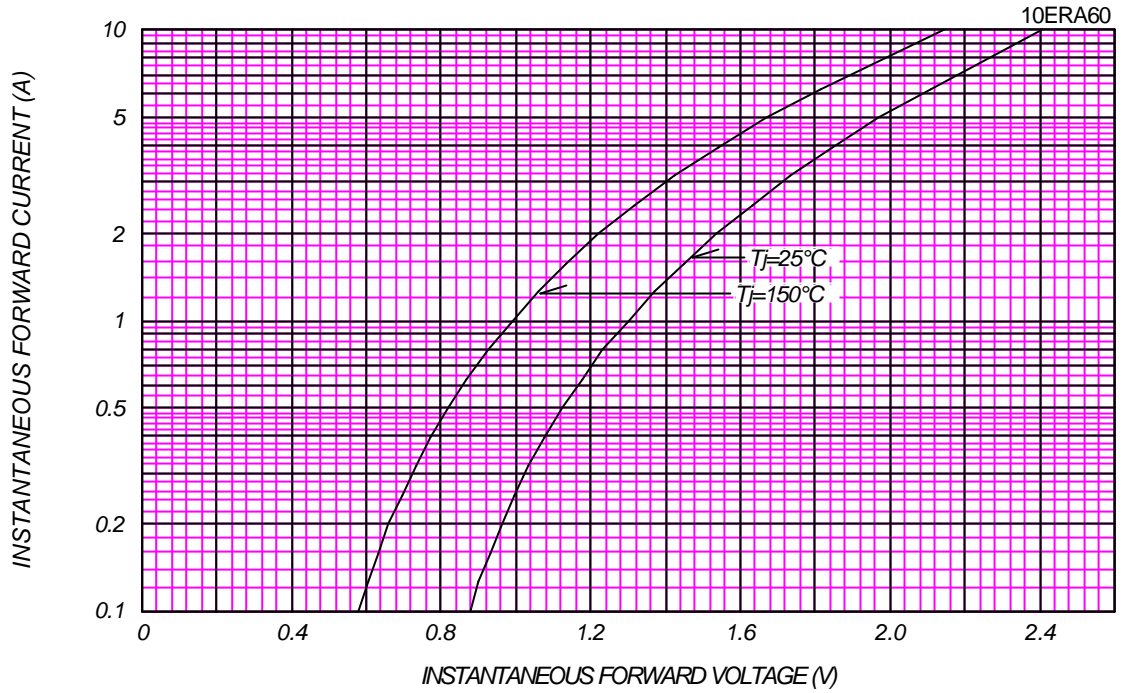
Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current	$I_{RM}$	$T_j=25^{\circ}\text{C}$ , $V_{RM}= V_{RRM}$	-	-	10	$\mu\text{A}$
Peak Forward Voltage	$V_{FM}$	$T_j=25^{\circ}\text{C}$ , $I_{FM}= 1 \text{ A}$	-	-	1.30	V
Reverse Recovery Time	trr	$I_{FM}= 1 \text{ A}$ , $-di/dt= 50 \text{ A}/\mu\text{s}$ , $T_a=25^{\circ}\text{C}$	-	-	80	ns
Thermal Resistance	Rth(j-l)	Junction to Lead	-	-	23	$^{\circ}\text{C}/\text{W}$
	Rth(j-a)	Junction to Ambient *1	-	-	100	$^{\circ}\text{C}/\text{W}$

\*1: Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)  
 $T_l$ =Lead Temperature

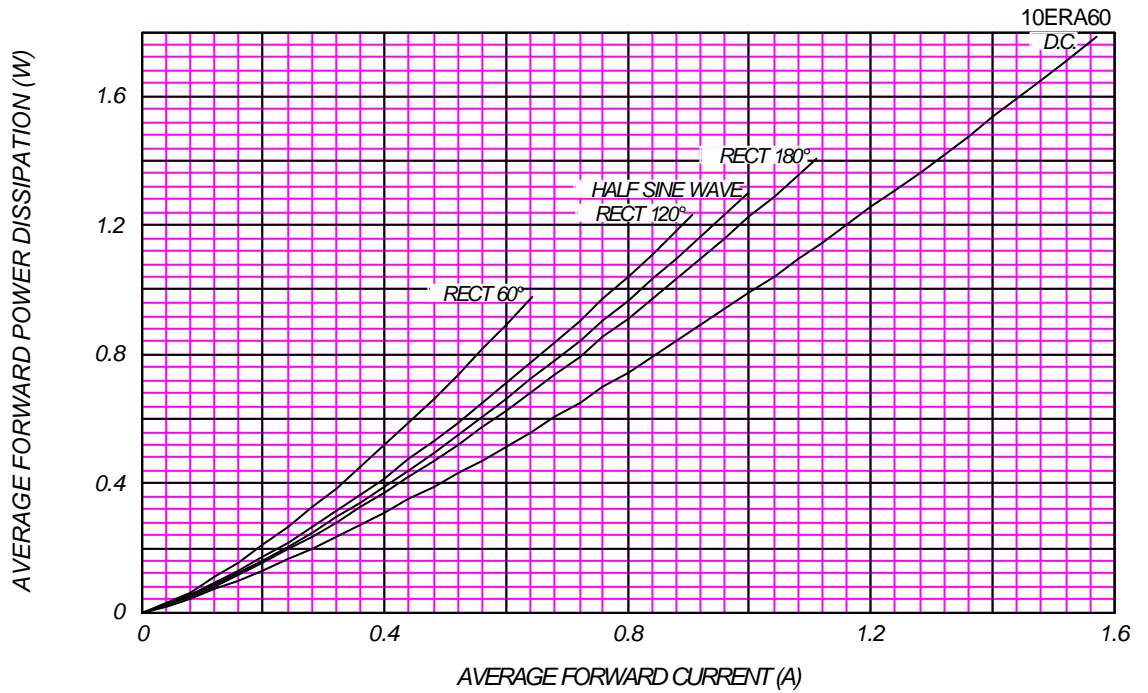
10ERA60 OUTLINE DRAWING (Dimensions in mm)



FORWARD CURRENT VS. VOLTAGE



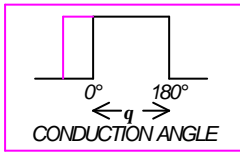
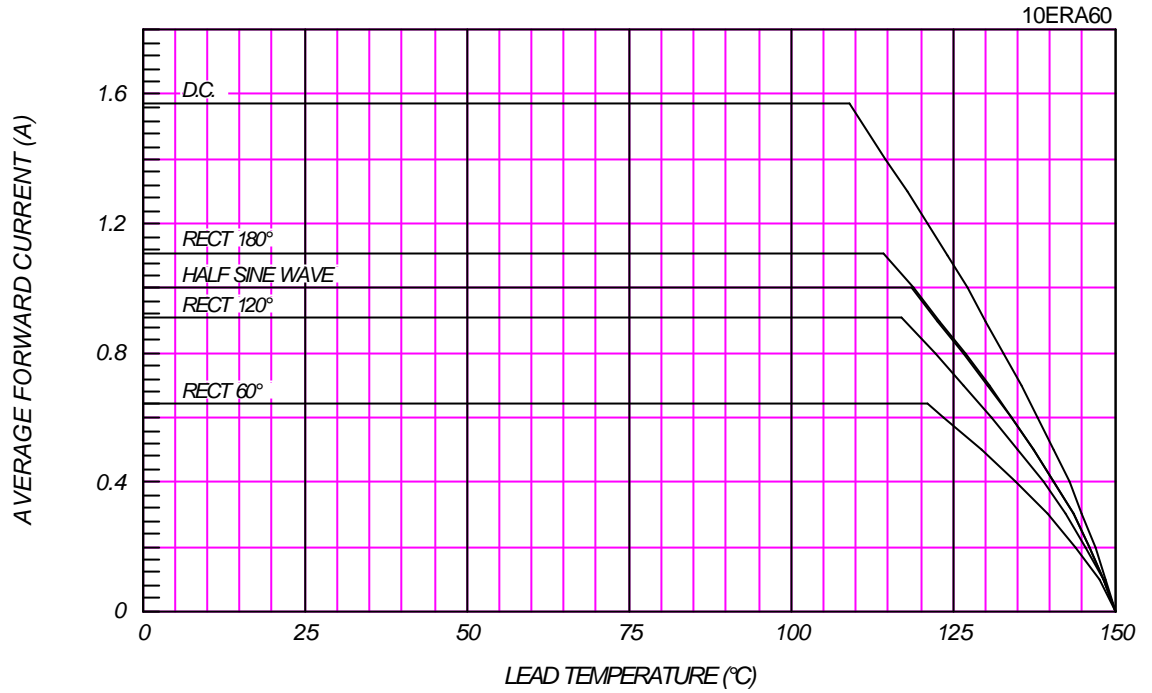
AVERAGE FORWARD POWER DISSIPATION





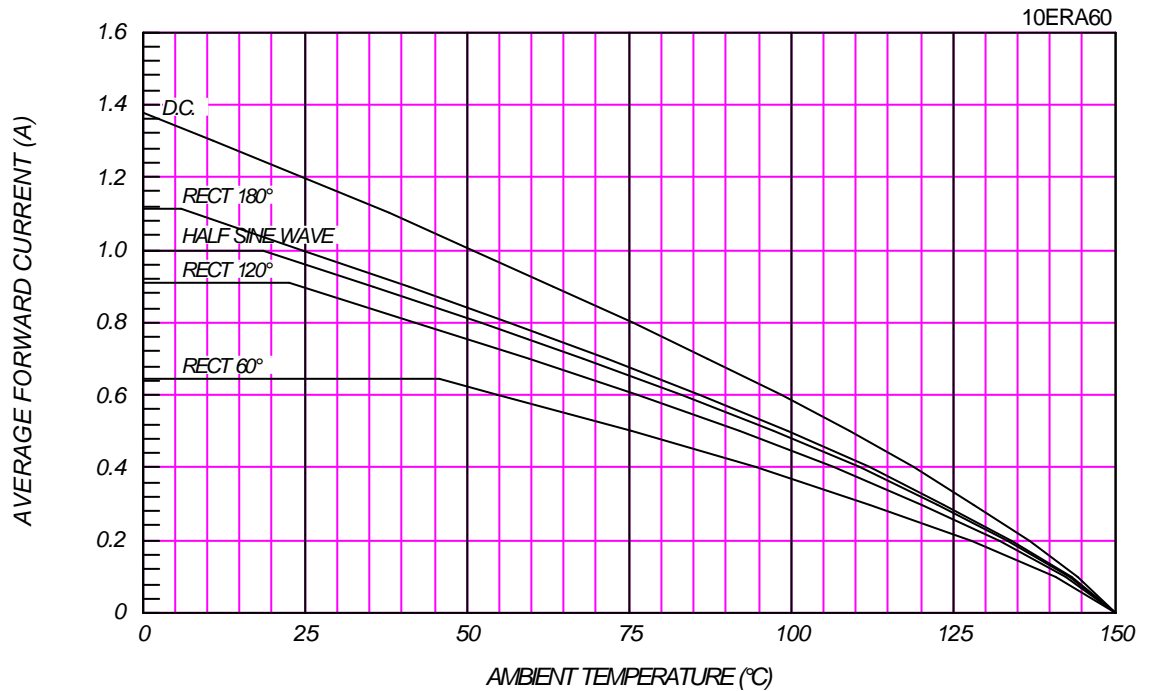
### AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

Without Fin or P.C. Board



### AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

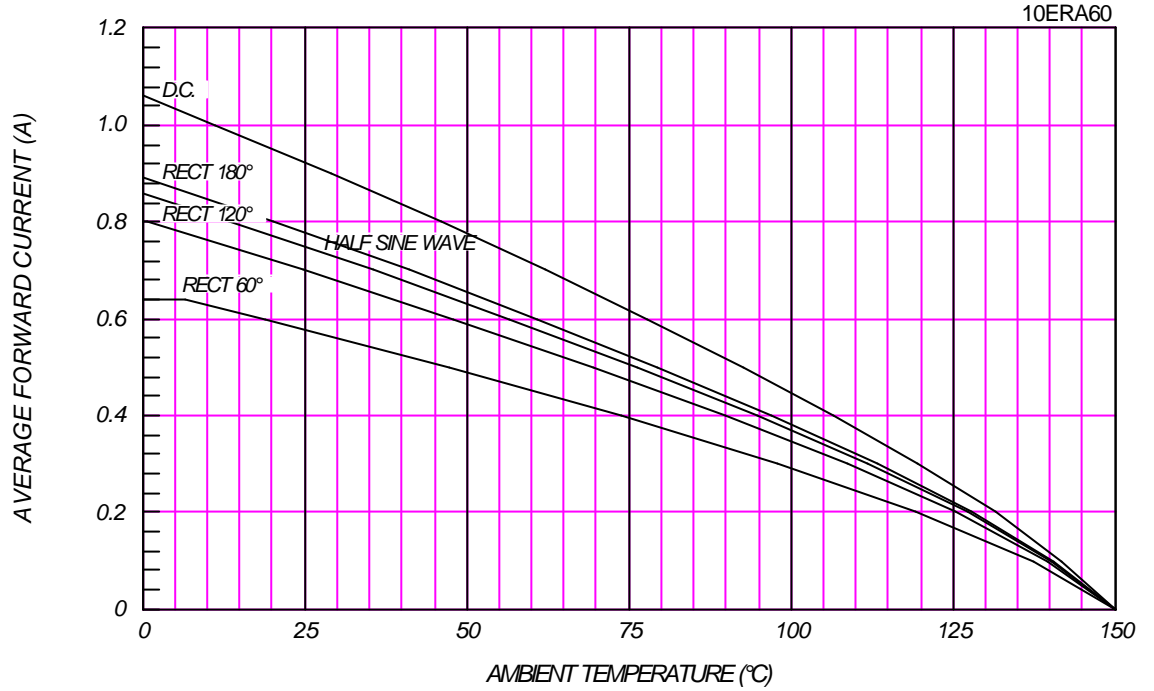
P.C. Board mounted (L=3mm, Print Land=7x7mm, Both Sides)





### AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Without Fin or P.C. Board



### SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

